

REMARKS

The above preliminary amendment is made to remove multiple dependencies from claim 7.

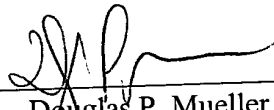
Applicants respectfully request that the preliminary amendment described herein be entered into the record prior to calculation of the filing fee and prior to examination and consideration of the above-identified application.

If a telephone conference would be helpful in resolving any issues concerning this communication, please contact Applicants' primary attorney-of record, Douglas P. Mueller (Reg. No. 30,300), at (612) 371.5237.

Respectfully submitted,

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By   
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DPM/rw

element mounted on the die bonding pad,

the die bonding pad being generally circular as viewed in plan and having an area larger than a bottom surface area of the light emitting element.

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5. An infrared data communication module comprising: a substrate having a surface for mounting a light emitting element, a light receiving element and an IC element; a protective member for covering each of the elements; and a molded body formed of a molding resin on said surface of the substrate to cover the protective member;

said surface of the substrate being formed with a recess for enhancing bond between the substrate and the molded body.

15 6. The infrared data communication module according to claim 5, wherein the recess is formed on said surface of the substrate at each of plural portions which avoid the protective member.

7. (AMENDED) The infrared data communication module according to claim 5 [or 6], wherein the recess is generally cylindrical.

8. A method of making infrared data communication modules each of which comprises a substrate having a surface for mounting a group of components which includes a light emitting element, a light receiving element and an IC element, and a molded body formed of a molding resin to entirely cover said surface of the substrate for sealing the group of components, said surface